### Silicon P-Channel MOS FET

# HITACHI

#### Application

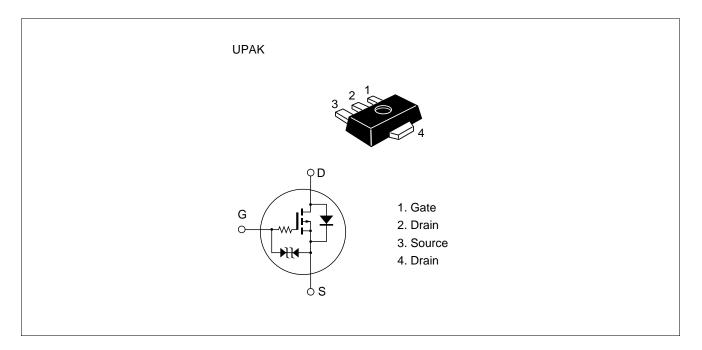
High speed power switching

Low voltage operation

#### Features

- Very low on-resistance
- High speed switching
- Suitable for camera or VTR motor drive circuit, power switch, solenoid drive and etc.

#### Outline





#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Drain to source voltage	V <sub>DSS</sub>	-12	V	
Gate to source voltage	V <sub>GSS</sub>	-7	V	
Drain current	I <sub>D</sub>	±2	А	
Drain peak current	l★1 D(pulse)	±4	А	
Body to drain diode reverse drain current	I <sub>DR</sub>	2	А	
Channel dissipation	Pch*2	1	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Notes: 1.  $PW \le 100 \ \mu s$ , duty cycle  $\le 10\%$ 

2. Value on the alumina ceramic board (12.5×20×0.7 mm).

3. Marking is "NY".

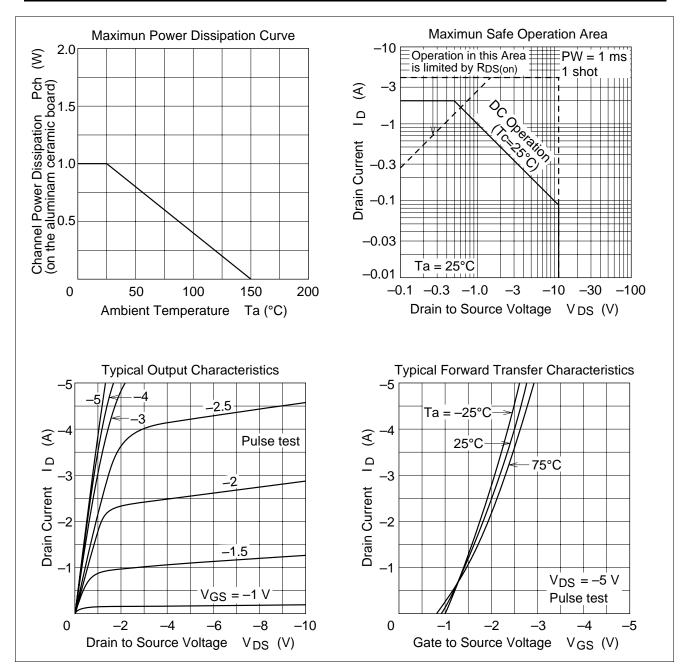
#### **Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-12	_	_	V	$I_{\rm D} = -1 \text{ mA}, V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±7	_	_	V	$I_{g} = \pm 10 \ \mu A, \ V_{DS} = 0$
Gate to source cutoff current	I <sub>GSS</sub>			±5	μΑ	$V_{GS} = \pm 6.5 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	—	_	-1	μΑ	$V_{\rm DS} = -8 \ V, \ V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	-0.4		-1.4	V	$I_{\rm D} = -100 \ \mu A, \ V_{\rm DS} = -5 \ V$
Static drain to source on state	$R_{DS(on)1}$	_	0.4	0.7	Ω	$I_{\rm D} = -0.5 \ {\rm A^{*1}}, \ V_{\rm GS} = -2.2 \ {\rm V}$
resistance	R <sub>DS(on)2</sub>	—	0.28	0.35	Ω	$I_{\rm D} = -1 \ {\rm A}^{*1}, \ {\rm V}_{\rm GS} = -4 \ {\rm V}$
Forward transfer admittance	y <sub>fs</sub>	1.0	2.3	_	S	$I_{\rm D} = -1 \ {\rm A}^{*1}, \ {\rm V}_{\rm DS} = -5 \ {\rm V}$
Input capacitance	Ciss	_	63	_	pF	$V_{\rm DS} = -5 \ V, \ V_{\rm GS} = 0,$
Output capacitance	Coss	_	180		pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	23	_	pF	
Turn-on time	t <sub>on</sub>	_	500	_	ns	$I_{\rm D} = -0.2 \ {\rm A^{*1}}, \ {\rm Vin} = -4 \ {\rm V},$
Turn-off time	t <sub>off</sub>	—	2860	_	ns	$R_{L} = 51 \Omega$

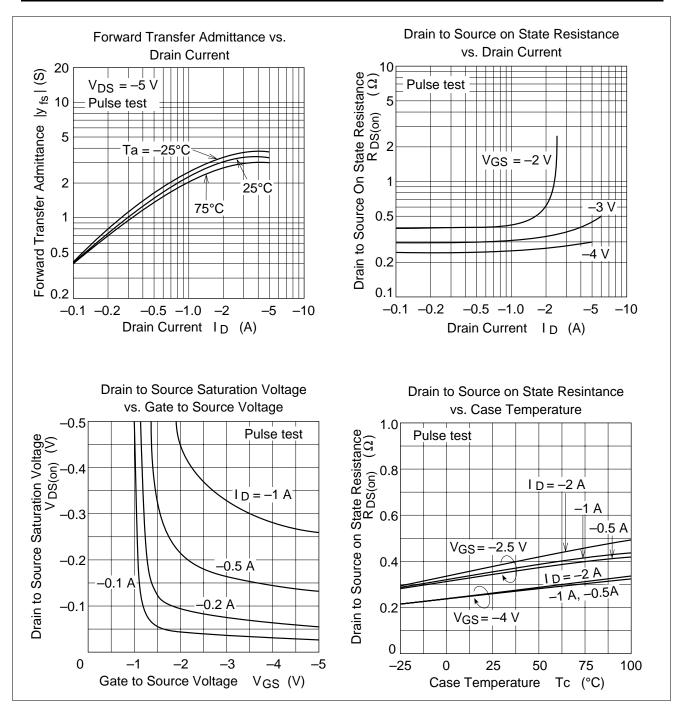
Note: 1. Pulse test

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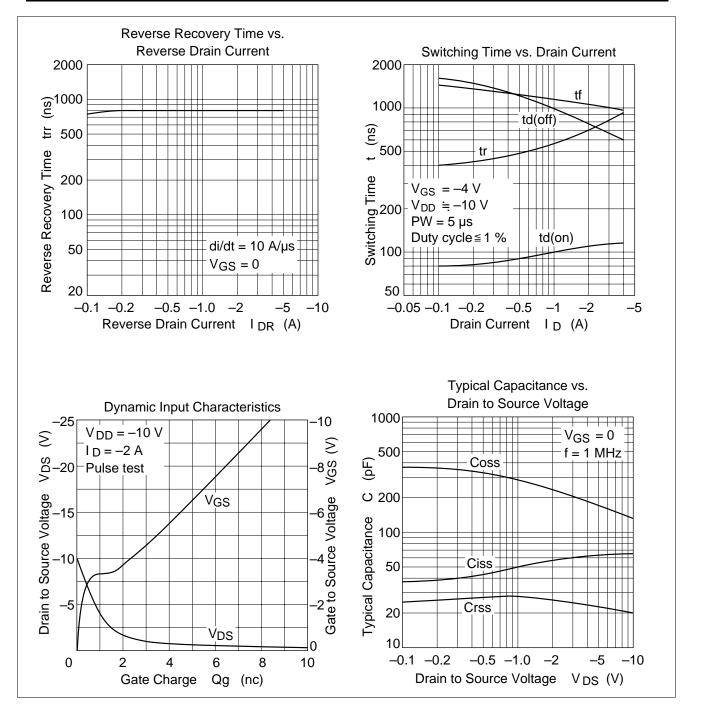


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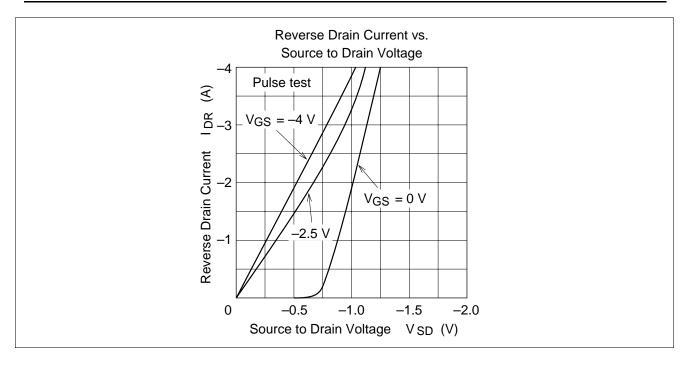


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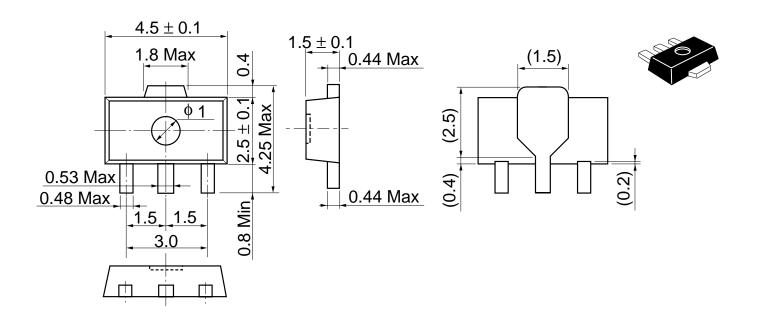
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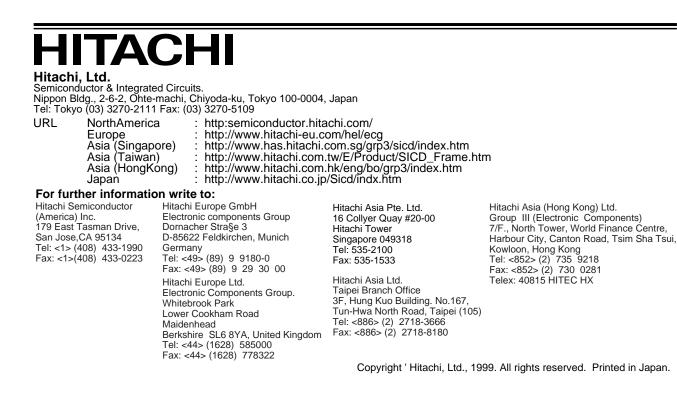
Unit: mm



Hitachi Code	UPAK
JEDEC	
EIAJ	Conforms
Weight (reference value)	0.050 g

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